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IKT-BI-3854-SKAP-INS



Design verification as per IEC/EN 61439

| Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees, calculated as per IEC 60890 Individual enclosure for wall mounting Pv C0 38 Starting enclosure for wall mounting Pv C0 33 Middle enclosure for wall mounting Pv C0 33 Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees, calculated as per IEC 60890 Individual enclosure for wall mounting Pv C0 77 Starting enclosure for wall mounting Pv C0 72 Middle enclosure for wall mounting Pv C0 66 | | | | |
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| Individual enclosure for wall mounting Py CO 36 Middle enclosure for wall mounting Py CO 36 Middle enclosure for wall mounting Py CO 36 Middle enclosure for wall mounting Py CO 37 Head dissipation, at an ambient temperature of 35°C, delta T.35 degrees, calculated as per IEC 68890 Individual enclosure for wall mounting Py CO 77 Starting enclosure for wall mounting Py CO 72 Middle enclosure for wall mounting Py CO 75 Middle enclosure for wall mounting Mests the product standard's requirements. Meets the product standard's requirements. In 10.2.5 Meets the product standard's requi | Technical data for design verification | | | |
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